SN54109, SN54LS109A, SN74109, SN74LS109A SDLS037 DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR December 1983 - Revised March 1988

 Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs

 Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent $J - \overline{K}$ positiveedge-triggered flip-flops. A low level at the preset or clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the J and \overline{K} inputs meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and \overline{K} inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding \overline{K} and tying J high. They also can perform as D-type flip-flops if J and \overline{K} are tied together.

The SN54109 and SN54LS109A are characterized for operation over the full military temperature range of -55° C to 125°C. The SN74109 and SN74LS109A are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)

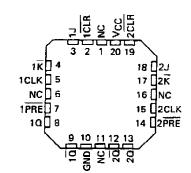
	in	OUT	PUTS			
PRE	CLR	CLK	J	к	a	ā
L	н	x	х	х	H	L
н	L	х	х	х	L .	н
L	L	х	х	х	нt	нţ
н	н	f	L	L	L	н
н	н	t	н	L	TOGO	GLE
н	н	t	Ł	н	00	<u>a</u> o
н	н	t	н	н	н	L
н	н	L	x	x		<u>o</u> o

[†] The output levels in this configuration are not guaranteed to meet the minimum levels for V_{OH} if the lows at preset and clear are near V_{1L} maximum. Furthermore, this configuration is nonstable; that is, it will not persist when preset or clear return to their inactive (high) level.

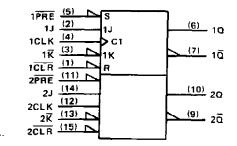
SN54109, SN54LS109A . . . J OR W PACKAGE SN74109 . . . N PACKAGE SN74LS109A . . . D OR N PACKAGE (TOP VIEW)

	1	\bigcup_{16}	□vcc
11	2	15	
1 K 🗆	3	14]2J
1CLK	4	13]2K
1PRE	5	12	2 <u>CLK</u>
10	6	11]2PRE
1 <u>0</u> [7	10]20
GND	8	9]2Õ
-			

SN54LS109A . . . FK PACKAGE (TOP VIEW)



logic symbol[‡]



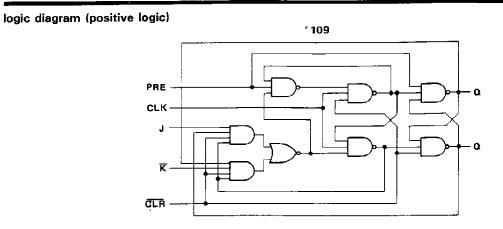
[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

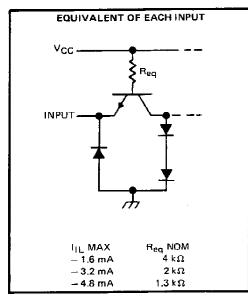


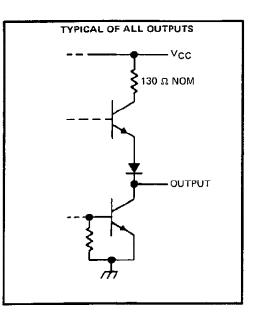
SN54109, SN74109 DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR



· ′109

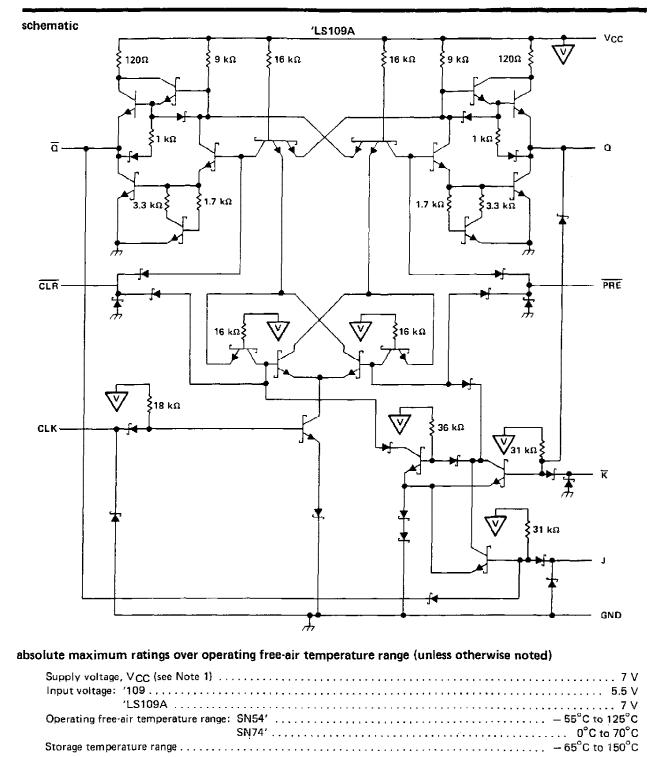
schematics of inputs and outputs







SN54109, SN54LS109A, SN74109, SN74LS109A DUAL J·K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR



NOTE 1: Voltage values are with respect to network ground terminal.

ž



SN54109, SN74109 DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

			SN54109		09	T	SN7410)9	UNIT	
			MIN	NOM	NOM MAX		MIN NOM MAX			
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V	
⊻ін	High-level input voltage		2	·		2			V	
۷iL	Low-level input voltage			-,	8.0			0.8	v	
юн	High-level output current				- 0.8			- 0.8	mA	
IOL	Low-level output current				16			16	mA	
÷	Pulse duration	CLK high or low	20			20				
t _w	Fuise duration	PRE or CLR low	20			20			ns	
tsu	Input setup time before CLK 1		10			10			ns	
t _{h_}	Input hold time-data after CLK1		6			6			ns	
ΤA	Operating free-air temperature		55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAR	AMETER		TEST CONDITI	onst		SN5410)9		SN7410		
						TYP [‡]	MAX	MIN	TYP‡	MAX	UNIT
VIK		V _{CC} = MIN,	l _l = − 12 mA	····			- 1.5			- 1.5	V
VQH		V _{CC} = MIN, I _{OH} = - 0.8 mA	V _{IH} = 2 V,	V _{IL} ≈ 0.8 V,	2.4	3,4		2.4	3.4		v
Val		V _{CC} = MIN, I _{OL} = 16 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,		0.2	0.4		0.2	0.4	v
η		V _{CC} = MAX,	Vj = 5.5 V				1			1	mА
	J or R						40		_	40	
1	CLR	Vcc = MAX,	V 2 4 V				160			160	
Η	PRE or CLK	¥CC - MOA,	vi - 2.4 v				80			80	μA
	J or K						- 1.6		·	- 1.6	
	CLR1	V MAX	N - 0 4 H				- 4.8			- 4.8	mΑ
ΊĽ	PRE	VCC = MAX,	v = 0.4 v				- 3.2			- 3.2	
	CLK						- 3.2			- 3.2	
'os§		V _{CC} = MAX			- 30		- 85	- 30	2 - a ui	- 85	mΑ
icc#		VCC = MAX,	See Note 2			9	15		9	15	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 V$, $T_A = 25 °C$.

⁵ Not more than one output should be shorted at a time.

[¶] Clear is tested with preset high and preset is tested with clear high.

Average per flip-flop.

NOTE 2: With all outputs open. ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN	ТҮР	MAX	UNIT	
fmax			·····		25	33		MHz
^t PLH	PRE	0				10	15	ns
τPHL		ā				23	35	ns
tPLH	CLR		RL = 400 Ω,	С _L = 15 рҒ		10	15	ns
tPHL .						17	25	ns
TPLH	CLK	QorQ				10	16	ns
^t PHL	GER	4014	_			18	28	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



SN54LS109A, SN74LS109A DUAL J- \overline{K} POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

			S	N54LS1	09A	S	N74LS1	A60	ÚNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
VCC	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7	Ι		0.8	V
он	High-level output current	1		- 0,4			- 0.4	mA	
IOL	Low-level output current			4			8	mA	
fclock	Clock frequency		0		25	0		25	MHz
		CLK high	25			25	_		
t _w	Pulse duration	PRE or CLR low	25			25			ns
		High-level data	35			35			
tsu	Setup time before CLK 1	Low-level data	25			25			ns
th	Hold time-data after CLK †		5			5			ns
TA	Operating free-air temperature		- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIO	Not	SN	154LS10	09A	SN	174LS10	09A	- דואט
FARAMETER		TEST CONDITIO	NS.	MIN	TYP‡	MAX	MIN	TYP‡	MAX	וואסן
VIK	VCC - MIN,	lj = - 18 mA				- 1.5		-	- 1.5	
VOH	V _{CC} = MIN, I _{OH} = - 0.4 mA	V _{IH} = 2 V,	V _{IL} = MAX,	2.5	3.4		2.7	3.4		v
	V _{CC} = MIN, I _{OL} = 4 mA	VIL = MAX,	V _{IH} ≠ 2 V,		0.25	0,4		0.25	0.4	
VOL	V _{CC} = MIN, I _{OL} = 8 mA	V _{IL} = MAX,	V _{1H} = 2 V,					0.35	0.5	
J, K or CLK	Vcc = MAX,	V1 = 7 V				0.1			0.1	- 1
CLR or PRE		4 1 - 3 4				0.2			0.2	mA
J, R or CLK	Vcc = MAX,	Vi = 2.7 V				20			20	
IH CLR or PRE		v - 2,7 v				40			40	μA
J, K or CLK	V _{CC} = MAX,	VI = 0.4 V				- 0.4			- 0.4	
IL CLR or PRE		v - 0,4 v				- 0.8		-	- 0.8	mA
OS§	V _{CC} = MAX,	See Note 4		- 20	_	- 100	- 20		- 100	mA
ICC (Total)	V _{CC} = MAX,	See Note 2			4	8		4	8	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions,

č

¹ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. §Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_D = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively with the minimum and maximum limits reduced to one half of their stated values.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITION	MIN	түр	мах	UNIT	
fmax					25	33		MHz
^t PLH	CLR, PRE		$R_{L} = 2 k\Omega, C_{L}$	= 15 pF		13	25	កន
^t PHL	or CLK					25	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



IMPORTANT NOTICE

Texas Instruments (TI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

TI warrants performance of its semiconductor products and related software to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Certain applications using semiconductor products may involve potential risks of death, personal injury, or severe property or environmental damage ("Critical Applications").

TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS.

Inclusion of TI products in such applications is understood to be fully at the risk of the customer. Use of TI products in such applications requires the written approval of an appropriate TI officer. Questions concerning potential risk applications should be directed to TI through a local SC sales office.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards should be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor does TI warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

Copyright © 1996, Texas Instruments Incorporated

6-Dec-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/30109B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/30109SEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30109SEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30109SFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/30109SFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74109N	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74109N	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74LS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109AN	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS109AN	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS109AN3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74LS109AN3	OBSOLETE	PDIP	Ν	16		TBD	Call TI	Call TI
SN74LS109ANE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS109ANE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



WWW.ti.com

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SNJ54LS109AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS109AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS109AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS109AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments Post Office Box 655303 Dallas, Texas 75265

Copyright © 2007, Texas Instruments Incorporated